



Emerging Liquid Alloy Intelligence: From Fundamental to Application Exploration

Guest Editors:

Prof. Dr. Zhigang Wu

School of Mechanical Science
and Engineering, Huazhong
University of Science and
Technology, 1037 Luoyu Rd,
Wuhan 430074, China

Prof. Dr. Wei Rao

Technical Institute of Physics and
Chemistry (TIPC), Chinese
Academy of Sciences (CAS)

Deadline for manuscript
submissions:

closed (10 November 2021)

Message from the Guest Editors

Dear Colleagues,

Being a high-fluidity, highly conductive material at room temperature, liquid alloys demonstrate numerous attractive advantages in many aspects, particularly for the deformable smart system in dynamic situations. Potentially, they will be an essential part of future soft intelligence and ultimately serve as an intimate partner of our daily life.

We invite original research papers, technical notes and shorter communications that focus on all areas on liquid alloy development at the micro/nanoscale, from fundamental research, including materials, interface, processing and devices, to application exploration, including biology, environment, electromagnetics, agriculture and robots, to contribute to this Special Issue. We are also looking for high-quality comprehensive reviews and perspectives that reference prior interest expressed to the Editorial Office and have received formal approval.





Editor-in-Chief

Message from the Editor-in-Chief

You are invited to contribute research articles or comprehensive reviews for consideration and publication in *Micromachines* (ISSN 2072-666X). *Micromachines* is published in the open access format. Research articles, reviews and other contents are released on the internet immediately after acceptance. The scientific community and the general public have unlimited free access to the content as soon as it is published. As an open access journal, *Micromachines* is supported by the authors or their institutes by payment of article processing charges (APC) for accepted papers. We are pleased to welcome you as our authors.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), PubMed, PMC, Ei Compendex, dblp, and other databases.

Journal Rank: JCR - Q2 (*Chemistry, Analytical*) / CiteScore - Q2 (*Mechanical Engineering*)

Contact Us

Micromachines Editorial Office
MDPI, St. Alban-Anlage 66
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/micromachines
micromachines@mdpi.com
[X@micromach_mdpi](https://x.com/micromach_mdpi)